

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-7. (Canceled).

8. (Currently Amended) A structure for mounting the ~~automobile~~-control unit of claim 22, wherein the ~~electronic circuit apparatus-control unit~~ is fixed on the interior of an automatic transmission assembly of an automobile, and wherein said cooling medium is ~~a~~-transmission fluid.

9. (Withdrawn and Currently Amended) A structure for mounting the ~~automobile~~-control unit of claim 22, wherein the ~~electronic circuit apparatus-control unit~~ is fixed on the interior of an engine compartment of an automobile, and wherein the cooling medium is an engine cooling water.

10. (Withdrawn and Currently Amended) A structure for mounting the ~~automobile~~-control unit of claim 22, wherein the ~~electronic circuit apparatus-control unit~~ is fixed on the interior of an engine intake pipe of an automobile, and wherein the cooling medium is the air that passes in the engine intake pipe.

11. (Withdrawn and Currently Amended) A structure for mounting the ~~automobile~~-control unit of claim 22, wherein at least two ~~electronic circuit apparatuses-control units~~ are stacked on top of each other, and wherein the passage for circulating cooling medium is provided in the stacked ~~electronic circuit apparatuses control units~~.

12.-20. (Canceled).

21. (Currently Amended) An automobile A control unit for controlling an engine or transmission assembly of an automobile comprising:

a multilayered wiring board mounted with at least two electronic components;

a polyimide wiring board mounted with at least one heat generating component;

a heat sink having a higher heat conductivity than those heat conductivities of the multilayered wiring board and the polyimide wiring board and having opposed first and second major surfaces, wherein the multilayered wiring board is fixed to one the first major surface of the heat sink via an adhesive and the polyimide wiring board is fixed to another the second major surface of the heat sink via a-an adhesive and is bent at at least one end, and a portion of the at least one end is fixed to the first major surface of the heat sink via an adhesive;

an external connection terminal to which the multilayered wiring board and/or and the polyimide wiring board is-are electrically connected;

bonding wires electrically connecting the multilayered wiring board and polyimide wiring board to the external connection terminal, wherein the bonding wires are provided only over the first major surface of the heat sink to which the multilayered wiring board and the portion of the at least one end of the polyimide wiring board are fixed; and

a thermosetting resin composition with which the entire surfaces of the multilayered wiring board and the polyimide wiring board, the bonding wires, a part of the heat sink and a part of the external connection terminal are integrally molded.

22. (Currently Amended) An automobile A control unit according to claim 21, wherein a part of a passage for circulating a cooling medium is formed in an external layer of the electronic circuit apparatus control unit.

23. (Currently Amended) An automobile A control unit according to claim 21, wherein the heat sink is made of a metal compound with electrical conductivity, and wherein the adhesive is formed by an insulating organic paste.

24. (Currently Amended) An automobile A control unit according to claim 21, wherein the heat sink is made of a clad material containing a copper alloy or copper.

25. (Currently Amended) An automobile A control unit according to claim 21, wherein the adhesive is made of a thermosetting resin composition containing an epoxy resin and an inorganic filler.

26. (Currently Amended) An automobile A control unit according to claim 21, wherein the multilayered wiring board comprises at least one ceramic substrate.

27. (Canceled).

28. (Currently Amended) An automobile A control unit according to claim 27, wherein the multilayered wiring board and the polyimide wiring board are electrically connected.

29. (Currently Amended) An automobile A control unit according to claim 22, wherein the part of the passage for circulating a cooling medium is formed in the

thermosetting resin composition.

30. (Currently Amended) ~~An automobile~~^A control unit according to claim 21, wherein the heat sink is made of a clad material having ~~copper-invar-copper layers a~~ layer comprising an alloy comprising iron and nickel clad on both sides with layers comprising copper.

31. (Canceled).